

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: :
 Belgacem Haba :
 Continuation of Serial No. :
 08/987,521 filed December 9, 1997 :
 Filed: Herewith :
 For: METHOD FOR FORMING A :
 MULTI-LAYER CIRCUIT ASSEMBLY :
 Date: June 23, 2000 :
 X

Assistant Commissioner for Patents
 Washington, D.C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

After according a filing date to the above-identified Rule 53(b) Continuation Application, please amend the application as follows:

In the Specification:

At page 1, line 1, please delete "This application".

At page 1, line 1, before "claims benefit of" insert --The present application is a continuation of United States Patent Application 08/987,521 filed December 9, 1997, which--.

In the Claims:

Amend claim 28 as follows:

28. (Twice Amended) A method of making a multi-layer circuit assembly comprising the steps of:
- (a) providing an inner dielectric element;